



RAYSTAR



SPECIFICATION



RAYSTAR

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SPECIFICATION

REX012864BYPP3N00000

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:

Contents

No.	Item	Page
1.	Revision History	4
2.	General Specification	4
3.	Module Coding System	5
4.	Interface Pin Function	6
5.	Outline Dimension	8
6.	Block Diagram	9
7.	Absolute Maximum Ratings	10
8.	Optics & Electrical Characteristics	11
9.	Reliability	15
10.	Inspection specification	16

1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2012/9/24	1		First issue

2. General Specification

The Features is described as follow:

- Module dimension: $45.24 \times 29.14 \times 2.05$ (max.) mm³
- Active area: 35.056×17.52 mm²
- Number of dots: 128 x 64
- Pixel Pitch: 0.274×0.274 mm²
- Pixel Size: 0.258×0.258 mm²
- Display Mode: Passive Matrix
- Duty: 1/64
- Display Color: (Yellow)

3. Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13
R	E	X	012864	B	Y	P	P	3	N	0	0	000

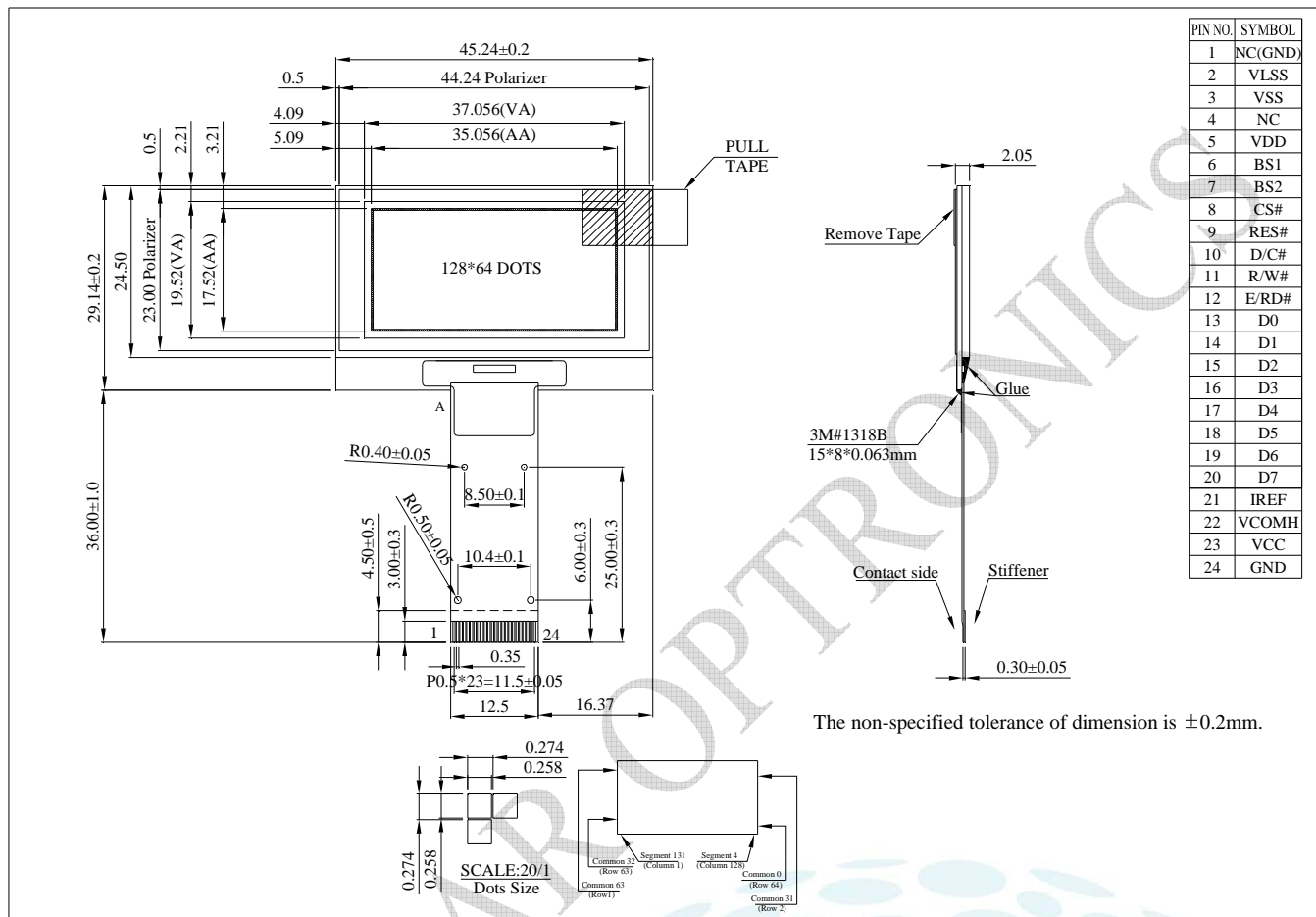
Item	Description		
1	R : Raystar Optronics Inc.		
2	E : OLED		
3	Display Type: C→Character Type, G→Graphic Type, T→TAB Type, X→COG Type		
4	Number of dots : 128 Dots x 64 Dots		
5	Serials code		
6	Emitting Color	A : Amber	R : RED
		B : Blue	Y : Yellow
		G : Green	W : White
7	Polarizer	P : With Polarizer ; N: Without Polarizer	
8	Display Mode	P : Passive Matrix ; A: Active Matrix	
9	Driver Voltage	3: 3.0 V ; 5: 5.0V	
10	Touch Panel	N : Without touch panel ; T: With touch panel	
11	Species	0:Normal , 1:Sunlight readable, 2:Transparent, 3:Flexible, 4:Lighting	
12	Grade code		
13	Serial No.	000: Sales code	

4. Interface Pin Function

No.	Symbol	Function															
1	NC(GND)	<i>Reserved Pin (Supporting Pin)</i> The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.															
2	VLSS	<i>Ground of Analog Circuit</i> This is an analog ground pin. It should be connected to VSS externally.															
3	VSS	<i>Ground of Logic Circuit</i> This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.															
4	NC	<i>Reserved Pin</i> The N.C. pins between function pins are reserved for compatible and flexible design.															
5	VDD	<i>Power Supply for Logic Circuit</i> This is a voltage supply pin. It must be connected to external source.															
6	BS1	<i>Communicating Protocol Select</i> These pins are MCU interface selection input. See the following table: <table><tr><td></td><td>68XX-parall el</td><td>80XX-parall el</td><td>Serial</td><td>I2C</td></tr><tr><td>BS1</td><td>0</td><td>1</td><td>0</td><td>1</td></tr><tr><td>BS2</td><td>1</td><td>1</td><td>0</td><td>0</td></tr></table>		68XX-parall el	80XX-parall el	Serial	I2C	BS1	0	1	0	1	BS2	1	1	0	0
	68XX-parall el	80XX-parall el	Serial	I2C													
BS1	0	1	0	1													
BS2	1	1	0	0													
7	BS2																
8	CS#	<i>Chip Select</i> This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low															
9	RES#	<i>Power Reset for Controller and Driver</i> This pin is reset signal input. When the pin is low, initialization of the chip is executed.															
10	D/C#	<i>Data/Command Control</i> This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams. When the pin is pulled high and serial interface mode is selected, the data at SDIN is treated as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection.															
11	R/W#	<i>Read/Write Select or Write</i> This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low.															

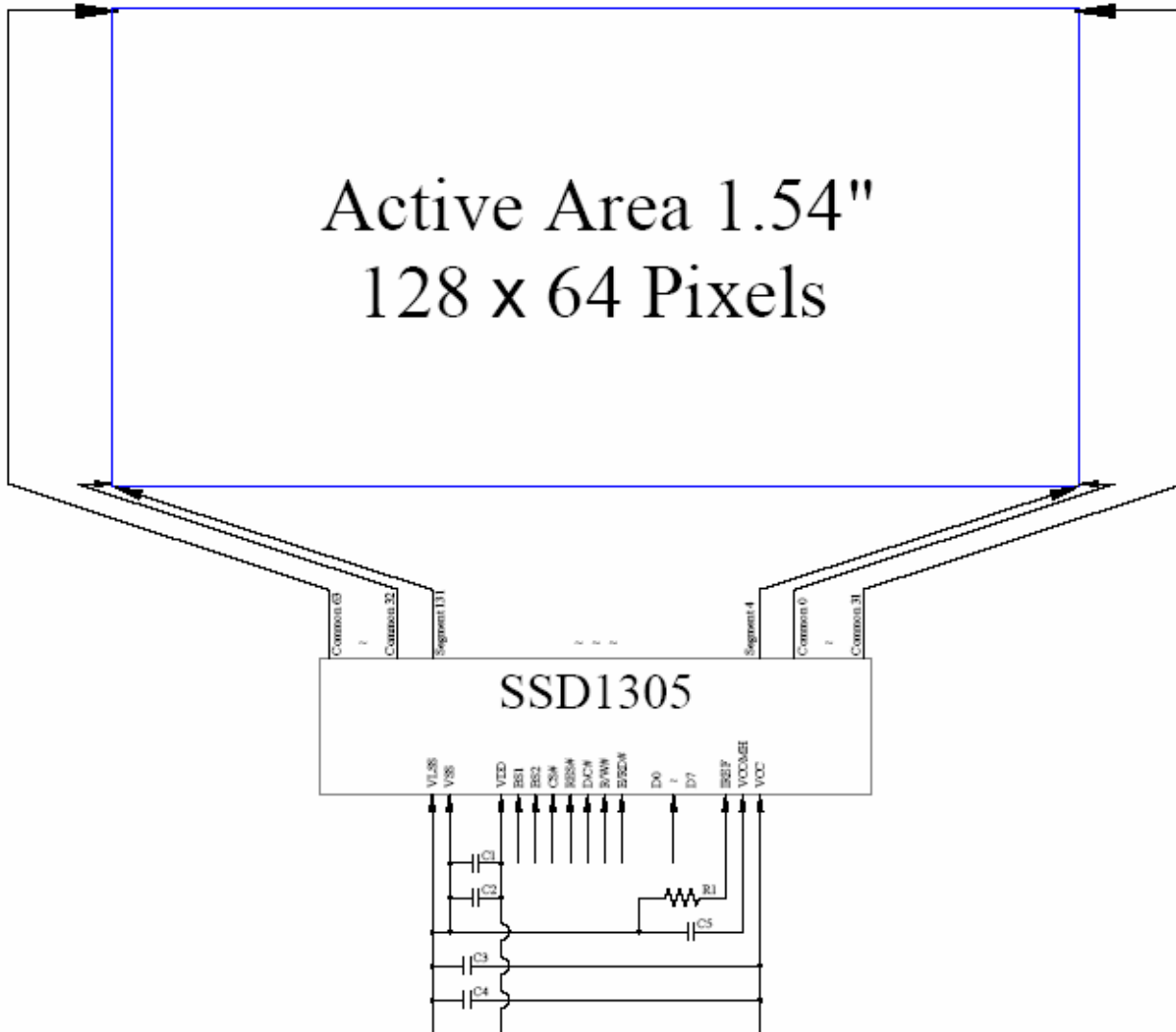
12	E/RD#	<p><i>Read/Write Enable or Read</i></p> <p>This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low.</p> <p>When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.</p>
13~20	D0~D7	<p><i>Host Data Input/Output Bus</i></p> <p>These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I2C mode is selected, D2 & D1 should be tied together and serve as SDAout & SDAin in application and D0 is the serial clock input SCL.</p>
21	IREF	<p><i>Current Reference for Brightness Adjustment</i></p> <p>This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 10μA.</p>
22	VCOMH	<p><i>Voltage Output High Level for COM Signal</i></p> <p>This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.</p>
23	VCC	<p><i>Power Supply for OEL Panel</i></p> <p>This is the most positive voltage supply pin of the chip. It must be supplied externally.</p>
24	GND	<p><i>Reserved Pin (Supporting Pin)</i></p> <p>The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground.</p>

5. Outline Dimension





6. Block Diagram



MCU Interface Selection: BS1 and BS2

Pins connected to MCU interface: CS#, RES#, D/C#, R/W#, E/RD#, and D0~D7

C1, C3: 0.1 μ F

C2: 4.7 μ F

C4: 10 μ F

C5: 4.7 μ F / 25V Tantalum Capacitor

R1: 910k Ω , $R1 = (\text{Voltage at IREF} - VSS) / IREF$

7. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1,2
Supply Voltage for Display	VCC	0	15	V	1,2
Operating Temperature	TOP	-40	80	°C	—
Storage Temperature	TSTG	-40	80	°C	—

Note 1: All the above voltages are on the basis of “VSS = 0V”.

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. “Optics & Electrical Characteristics”. If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

8. Optics & Electrical Characteristics

8.1 Optics Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Brightness	L_{br}	With Polarizer (Note 3)	100	-	-	cd/m ²
C.I.E. (Yellow)	(x) (y)	Without Polarizer	0.43 0.46	0.47 0.50	0.51 0.54	
Dark Room Contrast	CR		-	>2000:1	-	
View Angle			>160	-	-	degree

* Optical measurement taken at $V_{DD} = 2.8V$, $V_{CC} = 12.5V$.

Software configuration follows Section 4.4 Initialization.

8.2 DC Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage for Logic	V_{DD}		2.4	2.8	3.5	V
Supply Voltage for Display	V_{CC}	Note 3	14.5	15.0	15.5	V
High Level Input	V_{IH}	$I_{OUT} = 100\mu A$, 3.3MHz	$0.8 \times V_{DD}$	-	V_{DD}	V
Low Level Input	V_{IL}	$I_{OUT} = 100\mu A$, 3.3MHz	0	-	$0.2 \times V_{DD}$	V
High Level Output	V_{OH}	$I_{OUT} = 100\mu A$, 3.3MHz	$0.9 \times V_{DD}$	-	V_{DD}	V
Low Level Output	V_{OL}	$I_{OUT} = 100\mu A$, 3.3MHz	0	-	$0.1 \times V_{DD}$	V
Operating Current for V_{DD}	I_{DD}	Note 4 Note 5	--	180 180	300 300	μA μA
Operating Current for V_{CC}	I_{CC}	Note 4 Note 5	--	60 72	100 120	mA mA
Sleep Mode Current for V_{DD}	$I_{DD, SLEEP}$		-	1	5	μA
Sleep Mode Current for V_{CC}	$I_{CC, SLEEP}$		-	1	5	μA

Note 3: Brightness (L_{br}) and Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.

Note 4: $V_{DD} = 2.8V$, $V_{CC} = 12.5V$, 50% Display Area Turn on.

Note 5: $V_{DD} = 2.8V$, $V_{CC} = 12.5V$, 100% Display Area Turn on.

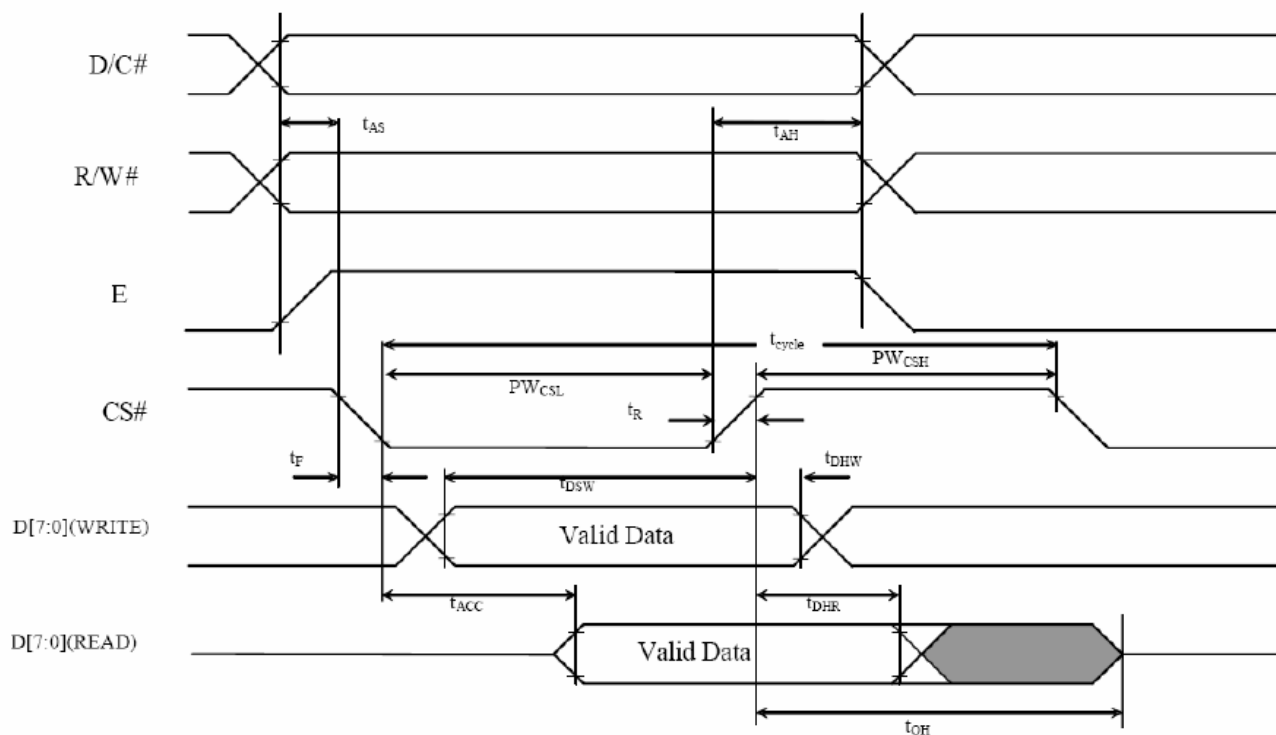
* Software configuration follows Section 4.4 Initialization.

8.3 AC Characteristics

8.3.1 68XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	System Cycle Time	300	-	ns
t_{AS}	Address Setup Time	0	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	7	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (Read) Chip Select Low Pulse width (Write)	120 60	-	ns
PW_{CSH}	Chip Select High Pulse Width (Read) Chip Select High Pulse Width (Write)	60 60	-	ns
t_R	Rise Time	-	15	ns
t_F	Fall Time	-	15	ns

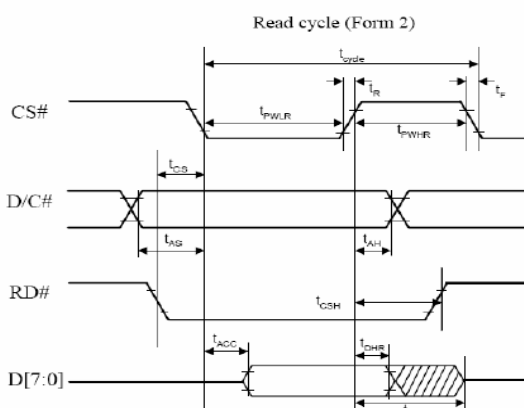
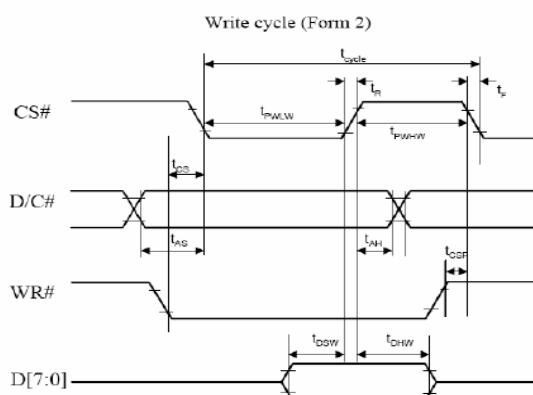
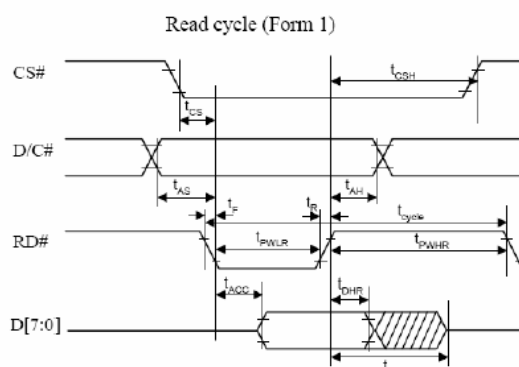
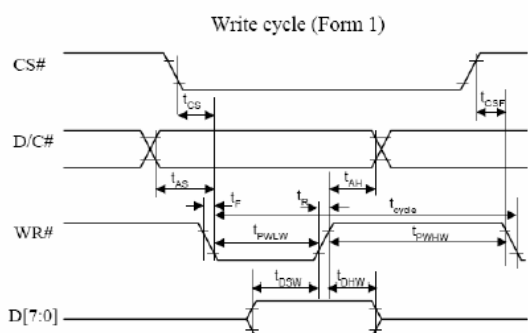
* ($V_{DD} - V_{SS} = 2.4V$ to $3.5V$, $T_a = 25^\circ C$)



8.3.2 80XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	ns
t_{AS}	Address Setup Time	10	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	7	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
t_{PWLR}	Read Low Time	120	-	ns
t_{PWLW}	Write Low Time	60	-	ns
t_{PWHR}	Read High Time	60	-	ns
t_{PWHW}	Write High Time	60	-	ns
t_{CS}	Chip Select Setup Time	0	-	ns
t_{CSH}	Chip Select Hold Time to Read Signal	0	-	ns
t_{CSF}	Chip Select Hold Time	20	-	ns
t_R	Rise Time	-	15	ns
t_F	Fall Time	-	15	ns

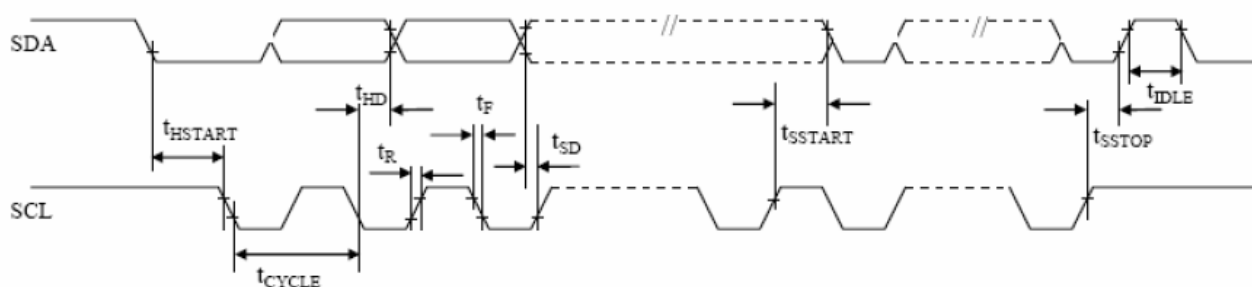
* ($V_{DD} - V_{SS} = 2.4V$ to $3.5V$, $T_a = 25^\circ C$)



8.3.4 I²C Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	2.5	-	us
t_{HSTART}	Start Condition Hold Time	0.6	-	us
t_{HD}	Data Hold Time (for "SDA _{OUT} " Pin) Data Hold Time (for "SDA _{IN} " Pin)	0 300	-	ns
t_{SD}	Data Setup Time	100	-	ns
	Start Condition Setup Time			
t_{SSTART}	(Only relevant for a repeated Start condition)	0.6	-	us
t_{SSTOP}	Stop Condition Setup Time	0.6	-	us
t_{R}	Rise Time for Data and Clock Pin		300	ns
t_{F}	Fall Time for Data and Clock Pin		300	ns
t_{IDLE}	Idle Time before a New Transmission can Start	1.3	-	us

* ($V_{\text{DD}} - V_{\text{SS}} = 2.4\text{V to } 3.5\text{V}$, $T_{\text{a}} = 25^{\circ}\text{C}$)



9. Reliability

9.1 Contents of Reliability Tests

Item	Conditions	Criteria
High Temperature Operation	80°C, 240 hrs	The operational functions work.
Low Temperature Operation	-40°C, 240 hrs	
High Temperature Storage	80°C, 240 hrs	
Low Temperature Storage	-40°C, 240 hrs	
HighTemperature/Humidity Storage	60°C, 90% RH, 240 hrs	
Thermal Shock	-40°C ⇔ 80°C, 24 cycles 1 hr dwell	

* The samples used for the above tests do not include polarizer.

* No moisture condensation is observed during tests.

9.2 Lifetime

End of lifetime is specified as 50% of initial brightness reached.

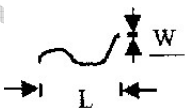
Parameter	Min	Max	Unit	Condition	Notes
Operating Life Time	10,000	-	hr	100 cd/m ² , 50% Checkerboard	6
	40,000	-	hr	100 cd/m ² , 50% Checkerboard	

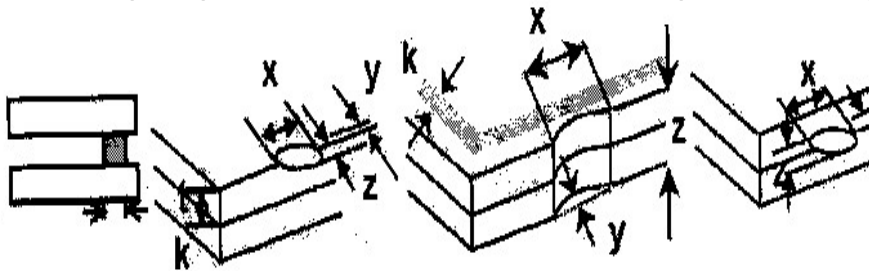
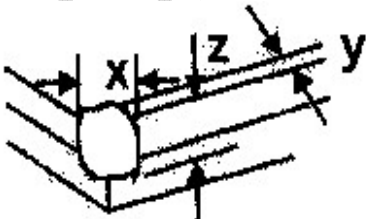
Note 6: The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

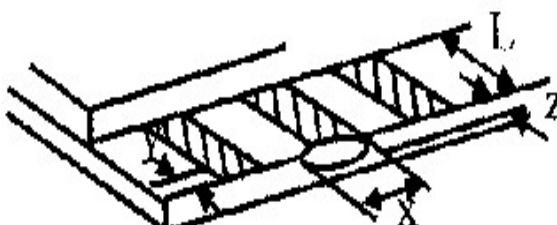
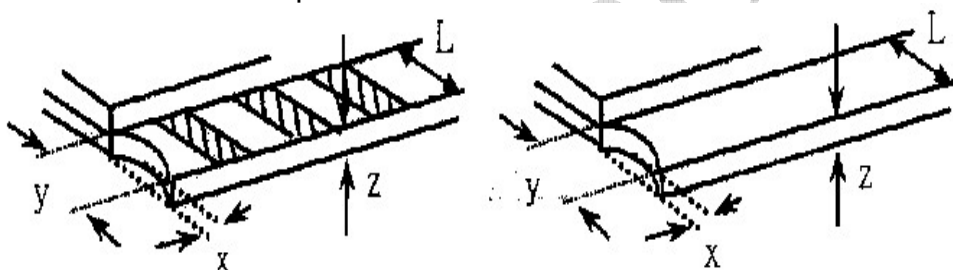
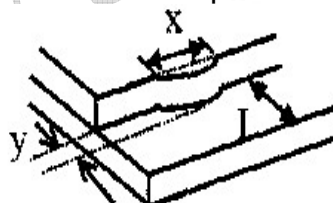
9.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.

10. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 Viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	Black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x+y)/2$	2.5												
		3.2 Line type : (As following drawing)  <table><tr><th>Length</th><th>Width</th><th>Acceptable QTY</th></tr><tr><td>---</td><td>$W \leq 0.02$</td><td>Accept no dense</td></tr><tr><td>$L \leq 3.0$</td><td>$0.02 < W \leq 0.03$</td><td rowspan="2">2</td></tr><tr><td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.05$</td></tr><tr><td>---</td><td>$0.05 < W$</td><td>As round type</td></tr></table>	Length	Width	Acceptable QTY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$
Length	Width	Acceptable QTY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	<div>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.</div> <table><tr><th>Size Φ</th><th>Acceptable QTY</th></tr><tr><td>$\Phi \leq 0.20$</td><td>Accept no dense</td></tr><tr><td>$0.20 < \Phi \leq 0.50$</td><td>3</td></tr><tr><td>$0.50 < \Phi \leq 1.00$</td><td>2</td></tr><tr><td>$1.00 < \Phi$</td><td>0</td></tr><tr><td>Total QTY</td><td>3</td></tr></table>	Size Φ	Acceptable QTY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total QTY	3	2.5
Size Φ	Acceptable QTY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total QTY	3														

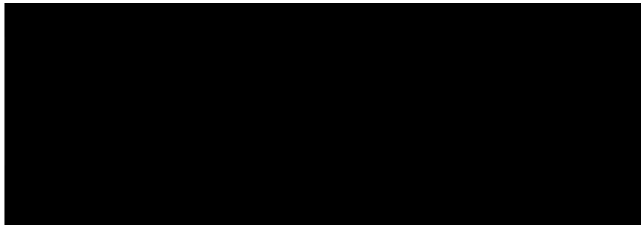
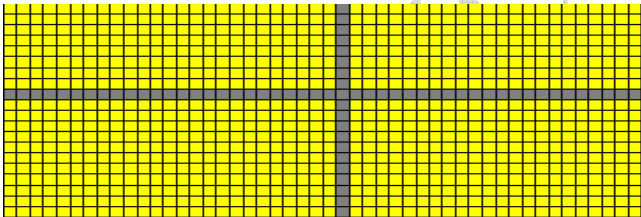
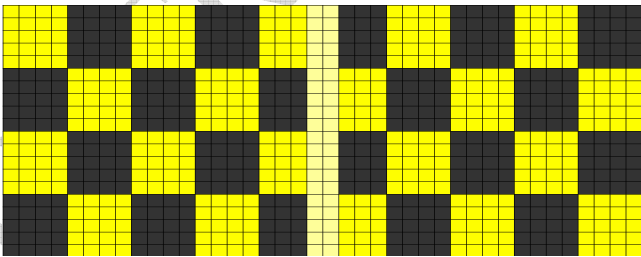
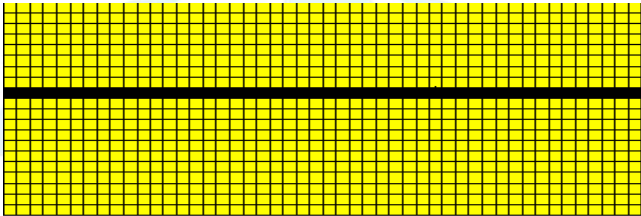
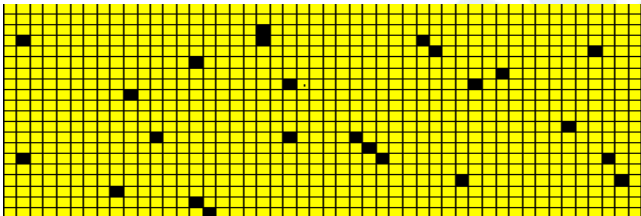
NO	Item	Criterion	AQL									
05	Scratches	Follow NO.3 Black spots, white spots, contamination										
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: Side length L: Electrode pad length:										
		6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:										
												
		<table><tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed 1/3k</td><td>$x \leq 1/8a$</td></tr></table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length										
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$										
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$										
		6.1.2 Corner crack:										
												
		<table><tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed 1/3k</td><td>$x \leq 1/8a$</td></tr></table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
z: Chip thickness	y: Chip width	x: Chip length										
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$										
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$										

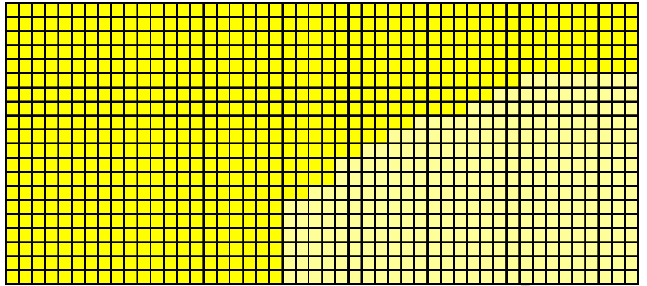
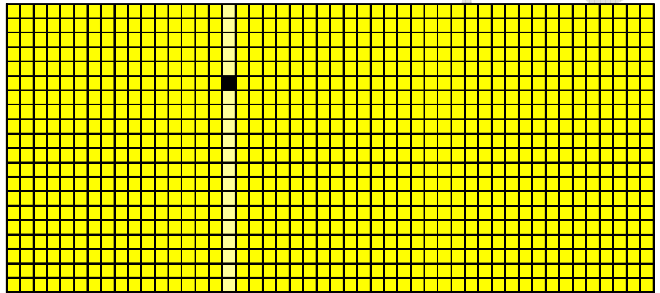
NO	Item	Criterion	AQL																
06	Glass crack	<p>Symbols :</p> <p>x: Chip length y: Chip width z: Chip thickness</p> <p>k: Seal width t: Glass thickness a: Side length</p> <p>L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p> <div></div> <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq 0.5\text{mm}$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> <p>6.2.2 Non-conductive portion:</p> <div></div> <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq L$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p> <div></div> <table><tr><td>y: width</td><td>x: length</td></tr><tr><td>$y \leq 1/3L$</td><td>$x \leq a$</td></tr></table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
		y: Chip width	x: Chip length	z: Chip thickness															
		$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$															
		y: Chip width	x: Chip length	z: Chip thickness															
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	With extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using Spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 Pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

Standard :

Defect item	Sorting	Defect judgment
No Display	Major	
Dark crisscross line	Major	
Short	Major	
Miss line	Major	
Wrong Display	Major	

Display Uneven	Major	
Dark dot and light line	Major	

Module Sample Estimate Feedback Sheet

Module Number : _____

1 、 Panel Specification :

1. Panel Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Numbers of Pixel :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. View Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Active Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Emitting Color :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Uniformity :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Operating Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Storage Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Others : _____		

2 、 Mechanical Specification :

1. PCB Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Frame Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Material of Frame :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Connector Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Fix Hole Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Thickness of PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Height of Frame to PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Height of Module :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

3 、 Relative Hole Size :

1. Pitch of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Hole size of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Mounting Hole size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Mounting Hole Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

>> **Go to page 2** <<

Module Number : _____

4 、 Electronic Characteristics of Module :

1.Input Voltage :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2.Supply Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3.Driving Voltage for OLED :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4.Contrast for OLED :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5.Negative Voltage Output :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6.Interface Function :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7.ESD test :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8.Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

5 、 Summary :
Sales signature : _____

Customer Signature : _____

Date : / /